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Details

Product Status	Last Time Buy
Core Processor	XC800
Core Size	8-Bit
Speed	25MHz
Connectivity	LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	27
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	38-TFSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-38
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc866l4fra3vbekxuma1

XC866

8-Bit Single-Chip Microcontroller

Microcontrollers



Never stop thinking

2.4 Pin Definitions and Functions

Table 3 Pin Definitions and Functions

Symbol	Pin Number	Type	Reset State	Function
P0		I/O		Port 0 Port 0 is a 6-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC.
P0.0	12	Hi-Z		TCK_0 JTAG Clock Input T12HR_1 CCU6 Timer 12 Hardware Run Input CC61_1 Input/Output of Capture/Compare channel 1 CLKOUT Clock Output RXDO_1 UART Transmit Data Output
P0.1	14	Hi-Z		TDI_0 JTAG Serial Data Input T13HR_1 CCU6 Timer 13 Hardware Run Input RXD_1 UART Receive Data Input COUT61_1 Output of Capture/Compare channel 1 EXF2_1 Timer 2 External Flag Output
P0.2	13	PU		CTRAP_2 CCU6 Trap Input TDO_0 JTAG Serial Data Output TXD_1 UART Transmit Data Output/ Clock Output
P0.3	2	Hi-Z		SCK_1 SSC Clock Input/Output COUT63_1 Output of Capture/Compare channel 3
P0.4	3	Hi-Z		MTSR_1 SSC Master Transmit Output/ Slave Receive Input CC62_1 Input/Output of Capture/Compare channel 2
P0.5	4		Hi-Z	MRST_1 SSC Master Receive Input/ Slave Transmit Output EXINT0_0 External Interrupt Input 0 COUT62_1 Output of Capture/Compare channel 2

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function
P3		I		Port 3 Port 3 is a bidirectional general purpose I/O port. It can be used as alternate functions for the CCU6.
P3.0	32		Hi-Z	CCPOS1_2 CCU6 Hall Input 1 CC60_0 Input/Output of Capture/Compare channel 0
P3.1	33		Hi-Z	CCPOS0_2 CCU6 Hall Input 0 CC61_2 Input/Output of Capture/Compare channel 1 COUT60_0 Output of Capture/Compare channel 0
P3.2	34		Hi-Z	CCPOS2_2 CCU6 Hall Input 2 CC61_0 Input/Output of Capture/Compare channel 1
P3.3	35		Hi-Z	COUT61_0 Output of Capture/Compare channel 1
P3.4	36		Hi-Z	CC62_0 Input/Output of Capture/Compare channel 2
P3.5	37		Hi-Z	COUT62_0 Output of Capture/Compare channel 2
P3.6	30		PD	<u>CTRAP_0</u> CCU6 Trap Input
P3.7	31		Hi-Z	EXINT4 External Interrupt Input 4 COUT63_0 Output of Capture/Compare channel 3

Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number	Type	Reset State	Function
V_{DDP}	18	–	–	I/O Port Supply (3.3 V/5.0 V) Also used by EVR and analog modules.
V_{SSP}	19	–	–	I/O Port Ground
V_{DDC}	8	–	–	Core Supply Monitor (2.5 V)
V_{SSC}	7	–	–	Core Supply Ground
V_{AREF}	25	–	–	ADC Reference Voltage
V_{AGND}	24	–	–	ADC Reference Ground
XTAL1	6	I	Hi-Z	External Oscillator Input (NC if not needed)
XTAL2	5	O	Hi-Z	External Oscillator Output (NC if not needed)
TMS	11	I	PD	Test Mode Select
RESET	38	I	PU	Reset Input
MBC¹⁾	1	I	PU	Monitor & BootStrap Loader Control

¹⁾ An external pull-up device in the range of 4.7 k Ω to 100 k Ω is required to enter user mode. Alternatively MBC can be tied to high if alternate functions (for debugging) of the pin are not utilized.

Functional Description
Table 7 CPU Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
F0 _H	B B Register Reset: 00 _H	Bit Field	B7	B6	B5	B4	B3	B2	B1	B0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
F8 _H	IP1 Interrupt Priority Register 1 Reset: 00 _H	Bit Field	PCCIP 3	PCCIP 2	PCCIP 1	PCCIP 0	PXM	PX2	PSSC	PADC
		Type	rw	rw	rw	rw	rw	rw	rw	rw
F9 _H	IPH1 Interrupt Priority Register 1 High Reset: 00 _H	Bit Field	PCCIP 3H	PCCIP 2H	PCCIP 1H	PCCIP 0H	PXMH	PX2H	PSSCH	PADC H
		Type	rw	rw	rw	rw	rw	rw	rw	rw

The system control SFRs can be accessed in the standard memory area (RMAP = 0).

Table 8 System Control Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0 or 1										
8F _H	SYSCON0 System Control Register 0 Reset: 00 _H	Bit Field	0							RMAP
		Type	r							rw
RMAP = 0										
BF _H	SCU_PAGE Page Register for System Control Reset: 00 _H	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rwh		
RMAP = 0, Page 0										
B3 _H	MODPISEL Peripheral Input Select Register Reset: 00 _H	Bit Field	0		JTAG TDIS	JTAG TCKS	0		EXINT 0IS	URRIS
		Type	r		rw	rw	r		rw	rw
B4 _H	IRCON0 Interrupt Request Register 0 Reset: 00 _H	Bit Field	0	EXINT 6	EXINT 5	EXINT 4	EXINT 3	EXINT 2	EXINT 1	EXINT 0
		Type	r	rwh	rwh	rwh	rwh	rwh	rwh	rwh
B5 _H	IRCON1 Interrupt Request Register 1 Reset: 00 _H	Bit Field	0			ADCS RC1	ADCS RC0	RIR	TIR	EIR
		Type	r			rwh	rwh	rwh	rwh	rwh
B7 _H	EXICON0 External Interrupt Control Register 0 Reset: 00 _H	Bit Field	EXINT3		EXINT2		EXINT1		EXINT0	
		Type	rw		rw		rw		rw	
BA _H	EXICON1 External Interrupt Control Register 1 Reset: 00 _H	Bit Field	0		EXINT6		EXINT5		EXINT4	
		Type	r		rw		rw		rw	
BB _H	NMICON NMI Control Register Reset: 00 _H	Bit Field	0	NMI ECC	NMI VDDP	NMI VDD	NMI OCDS	NMI FLASH	NMI PLL	NMI WDT
		Type	r	rw	rw	rw	rw	rw	rw	rw
BC _H	NMISR NMI Status Register Reset: 00 _H	Bit Field	0	FNMI ECC	FNMI VDDP	FNMI VDD	FNMI OCDS	FNMI FLASH	FNMI PLL	FNMI WDT
		Type	r	rwh	rwh	rwh	rwh	rwh	rwh	rwh
BD _H	BCON Baud Rate Control Register Reset: 00 _H	Bit Field	BGSEL		0	BREN	BRPRE			R
		Type	rw		r	rw	rw			rw
BE _H	BG Baud Rate Timer/Reload Register Reset: 00 _H	Bit Field	BR_VALUE							
		Type	rw							
E9 _H	FDCON Fractional Divider Control Register Reset: 00 _H	Bit Field	BGS	SYNEN	ERRSY N	EOFSY N	BRK	NDOV	FDM	FDEN
		Type	rw	rw	rwh	rwh	rwh	rwh	rw	rw
EA _H	FDSTEP Fractional Divider Reload Register Reset: 00 _H	Bit Field	STEP							
		Type	rw							
EB _H	FDRES Fractional Divider Result Register Reset: 00 _H	Bit Field	RESULT							
		Type	rh							
RMAP = 0, Page 1										

Functional Description
Table 8 System Control Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
B3 _H	ID Identity Register Reset: 01_H	Bit Field	PRODIG						VERID	
		Type	r						r	
B4 _H	PMCON0 Power Mode Control Register 0 Reset: 00_H	Bit Field	0	WDT RST	WKRS	WK SEL	SD	PD	WS	
		Type	r	rwh	rwh	rw	rw	rwh	rw	
B5 _H	PMCON1 Power Mode Control Register 1 Reset: 00_H	Bit Field	0				T2_DIS	CCU _DIS	SSC _DIS	ADC _DIS
		Type	r				rw	rw	rw	rw
B6 _H	OSC_CON OSC Control Register Reset: 08_H	Bit Field	0			OSC PD	XPD	OSC SS	ORD RES	OSCR
		Type	r			rw	rw	rw	rwh	rh
B7 _H	PLL_CON PLL Control Register Reset: 20_H	Bit Field	NDIV				VCO BYP	OSC DISC	RESLD	LOCK
		Type	rw				rw	rw	rwh	rh
BA _H	CMCON Clock Control Register Reset: 00_H	Bit Field	VCO SEL	0			CLKREL			
		Type	rw	r			rw			
BB _H	PASSWD Password Register Reset: 07_H	Bit Field	PASS					PROTE CT_S	MODE	
		Type	w					rh	rw	
BC _H	FEAL Flash Error Address Register Low Reset: 00_H	Bit Field	ECCERRADDR[7:0]							
		Type	rh							
BD _H	FEAH Flash Error Address Register High Reset: 00_H	Bit Field	ECCERRADDR[15:8]							
		Type	rh							
BE _H	COCON Clock Output Control Register Reset: 00_H	Bit Field	0	TLEN	COUT S	COREL				
		Type	r	rw	rw	rw				
E9 _H	MISC_CON Miscellaneous Control Register Reset: 00_H	Bit Field	0							DFLAS HEN
		Type	r							rwh
RMAP = 0, Page 3										
B3 _H	XADDRH On-Chip XRAM Address Higher Order Reset: F0_H	Bit Field	ADDRH							
		Type	rw							

The WDT SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 9 WDT Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
BB _H	WDTCON Watchdog Timer Control Register Reset: 00_H	Bit Field	0	WINB EN	WDT PR	0	WDT EN	WDT RS	WDT IN	
		Type	r	rw	rh	r	rw	rwh	rw	
BC _H	WDTREL Watchdog Timer Reload Register Reset: 00_H	Bit Field	WDTREL							
		Type	rw							
BD _H	WDTWINB Watchdog Window-Boundary Count Register Reset: 00_H	Bit Field	WDTWINB							
		Type	rw							
BE _H	WDTL Watchdog Timer Register Low Reset: 00_H	Bit Field	WDT[7:0]							
		Type	rh							
BF _H	WDTH Watchdog Timer Register High Reset: 00_H	Bit Field	WDT[15:8]							
		Type	rh							

Functional Description
Table 10 Port Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
B1 _H	P3_ALTSSEL1 Reset: 00 _H P3 Alternate Select 1 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 3										
80 _H	P0_OD Reset: 00 _H P0 Open Drain Control Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
90 _H	P1_OD Reset: 00 _H P1 Open Drain Control Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
B0 _H	P3_OD Reset: 00 _H P3 Open Drain Control Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

The ADC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 11 ADC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
D1 _H	ADC_PAGE Reset: 00_H Page Register for ADC	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rwh		
RMAP = 0, Page 0										
CA _H	ADC_GLOBCTR Reset: 30_H Global Control Register	Bit Field	ANON	DW	CTC		0			
		Type	rw	rw	rw		r			
CB _H	ADC_GLOBSTR Reset: 00_H Global Status Register	Bit Field	0		CHNR			0	SAM PLE	BUSY
		Type	r		rh			r	rh	rh
CC _H	ADC_PRAR Reset: 00_H Priority and Arbitration Register	Bit Field	ASEN1	ASEN0	0	ARBM	CSM1	PRI01	CSM0	PRI00
		Type	rw	rw	r	rw	rw	rw	rw	rw
CD _H	ADC_LCBR Reset: B7_H Limit Check Boundary Register	Bit Field	BOUND1				BOUND0			
		Type	rw				rw			
CE _H	ADC_INPCR0 Reset: 00_H Input Class Register 0	Bit Field	STC							
		Type	rw							
CF _H	ADC_ETRCR Reset: 00_H External Trigger Control Register	Bit Field	SYNEN 1	SYNEN 0	ETRSEL1			ETRSEL0		
		Type	rw	rw	rw			rw		
RMAP = 0, Page 1										
CA _H	ADC_CHCTR0 Reset: 00_H Channel Control Register 0	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CB _H	ADC_CHCTR1 Reset: 00_H Channel Control Register 1	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CC _H	ADC_CHCTR2 Reset: 00_H Channel Control Register 2	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CD _H	ADC_CHCTR3 Reset: 00_H Channel Control Register 3	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CE _H	ADC_CHCTR4 Reset: 00_H Channel Control Register 4	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CF _H	ADC_CHCTR5 Reset: 00_H Channel Control Register 5	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
D2 _H	ADC_CHCTR6 Reset: 00_H Channel Control Register 6	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
D3 _H	ADC_CHCTR7 Reset: 00_H Channel Control Register 7	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
RMAP = 0, Page 2										

Functional Description

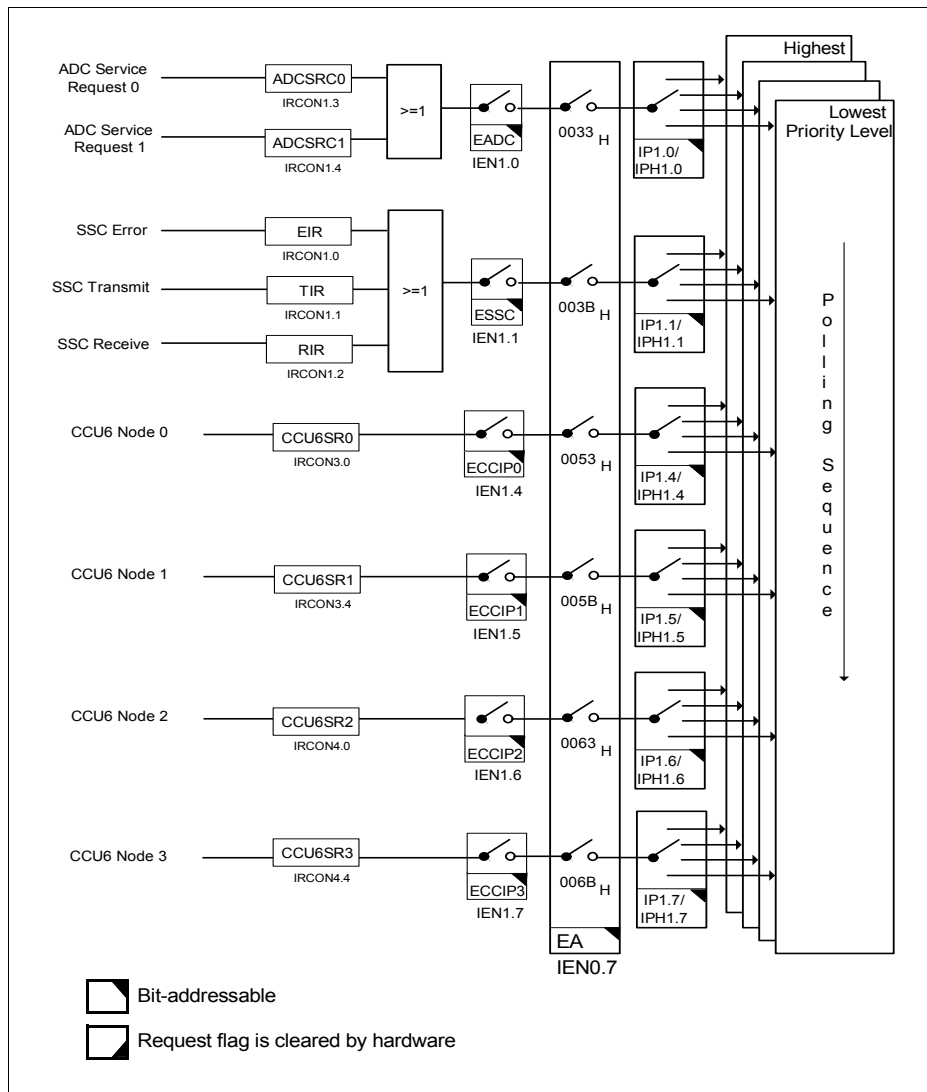


Figure 16 Interrupt Request Sources (Part 3)

Table 17 Interrupt Vector Addresses (cont'd)

XINTR6	0033 _H	ADC	EADC	IEN1
XINTR7	003B _H	SSC	ESSC	
XINTR8	0043 _H	External Interrupt 2	EX2	
XINTR9	004B _H	External Interrupt 3	EXM	
		External Interrupt 4		
		External Interrupt 5		
		External Interrupt 6		
XINTR10	0053 _H	CCU6 INP0	ECCIP0	
XINTR11	005B _H	CCU6 INP1	ECCIP1	
XINTR12	0063 _H	CCU6 INP2	ECCIP2	
XINTR13	006B _H	CCU6 INP3	ECCIP3	

3.5 Parallel Ports

The XC866 has 27 port pins organized into four parallel ports, Port 0 (P0) to Port 3 (P3). Each pin has a pair of internal pull-up and pull-down devices that can be individually enabled or disabled. Ports P0, P1 and P3 are bidirectional and can be used as general purpose input/output (GPIO) or to perform alternate input/output functions for the on-chip peripherals. When configured as an output, the open drain mode can be selected. Port P2 is an input-only port, providing general purpose input functions, alternate input functions for the on-chip peripherals, and also analog inputs for the Analog-to-Digital Converter (ADC).

Bidirectional Port Features:

- Configurable pin direction
- Configurable pull-up/pull-down devices
- Configurable open drain mode
- Transfer of data through digital inputs and outputs (general purpose I/O)
- Alternate input/output for on-chip peripherals

Input Port Features:

- Configurable input driver
- Configurable pull-up/pull-down devices
- Receive of data through digital input (general purpose input)
- Alternate input for on-chip peripherals
- Analog input for ADC module

Functional Description

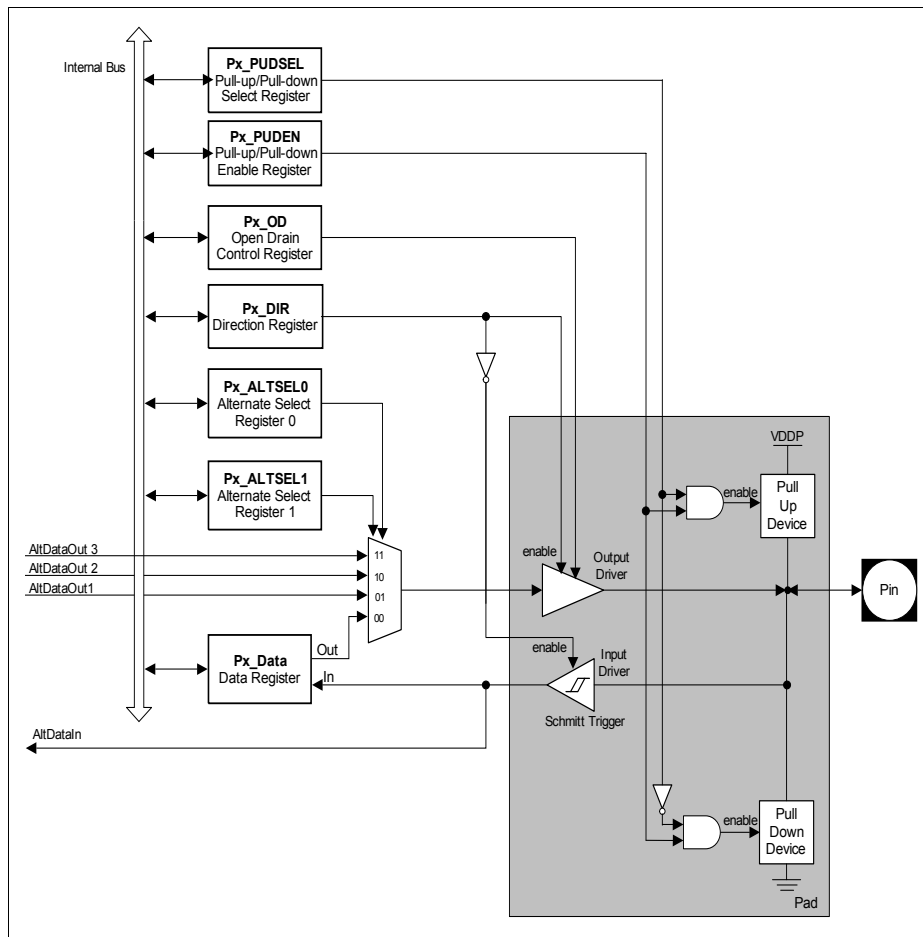


Figure 18 General Structure of Bidirectional Port

3.7 Reset Control

The XC866 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC866 is first powered up, the status of certain pins (see [Table 20](#)) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin $\overline{\text{RESET}}$ must be asserted until V_{DDC} reaches $0.9 \cdot V_{\text{DDC}}$. The delay of external reset can be realized by an external capacitor at $\overline{\text{RESET}}$ pin. This capacitor value must be selected so that V_{RESET} reaches 0.4 V, but not before V_{DDC} reaches $0.9 \cdot V_{\text{DDC}}$.

A typical application example is shown in [Figure 21](#). V_{DDP} capacitor value is 300 nF. V_{DDC} capacitor value is 220 nF. The capacitor connected to $\overline{\text{RESET}}$ pin is 100 nF.

Typically, the time taken for V_{DDC} to reach $0.9 \cdot V_{\text{DDC}}$ is less than 50 μs once V_{DDP} reaches 2.3V. Hence, based on the condition that 10% to 90% V_{DDP} (slew rate) is less than 500 μs , the $\overline{\text{RESET}}$ pin should be held low for 500 μs typically. See [Figure 22](#).

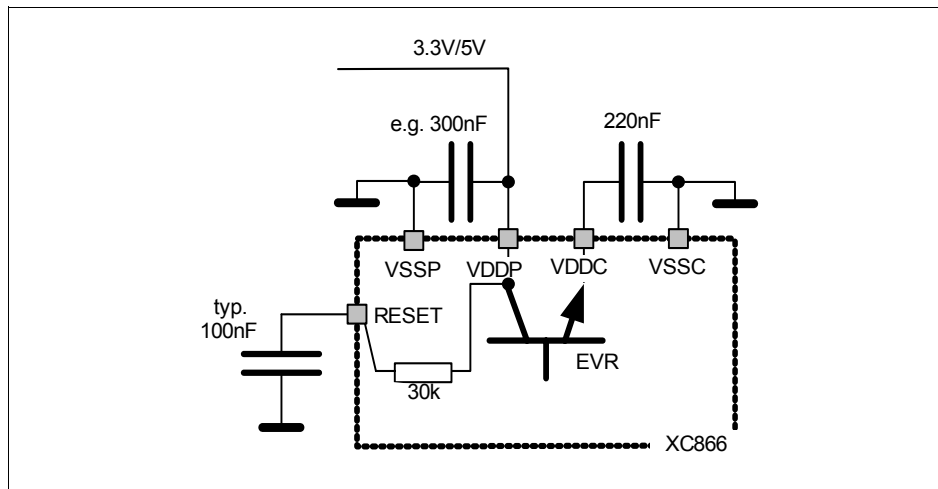


Figure 21 Reset Circuitry

Functional Description

For power saving purposes, the clocks may be disabled or slowed down according to [Table 23](#).

Table 23 System frequency ($f_{\text{sys}} = 80 \text{ MHz}$)

Power Saving Mode	Action
Idle	Clock to the CPU is disabled.
Slow-down	Clocks to the CPU and all the peripherals, including CCU6, are divided by a common programmable factor defined by bit field CMCON.CLKREL.
Power-down	Oscillator and PLL are switched off.

Functional Description

- 8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG

The following formulas calculate the final baud rate without and with the fractional divider respectively:

$$\text{baud rate} = \frac{f_{\text{PCLK}}}{16 \times 2^{\text{BRPRE}} \times (\text{BR_VALUE} + 1)} \quad \text{where } 2^{\text{BRPRE}} \times (\text{BR_VALUE} + 1) > 1$$

$$\text{baud rate} = \frac{f_{\text{PCLK}}}{16 \times 2^{\text{BRPRE}} \times (\text{BR_VALUE} + 1)} \times \frac{\text{STEP}}{256}$$

The maximum baud rate that can be generated is limited to $f_{\text{PCLK}}/32$. Hence, for a module clock of 26.7 MHz, the maximum achievable baud rate is 0.83 MBaud.

Standard LIN protocol can support a maximum baud rate of 20kHz, the baud rate accuracy is not critical and the fractional divider can be disabled. Only the prescaler is used for auto baud rate calculation. For LIN fast mode, which supports the baud rate of 20kHz to 115.2kHz, the higher baud rates require the use of the fractional divider for greater accuracy.

Table 26 lists the various commonly used baud rates with their corresponding parameter settings and deviation errors. The fractional divider is disabled and a module clock of 26.7 MHz is used.

Table 26 Typical Baud rates for UART with Fractional Divider disabled

Baud rate	Prescaling Factor (2^{BRPRE})	Reload Value (BR_VALUE + 1)	Deviation Error
19.2 kBaud	1 (BRPRE=000 _B)	87 (57 _H)	-0.22 %
9600 Baud	1 (BRPRE=000 _B)	174 (AE _H)	-0.22 %
4800 Baud	2 (BRPRE=001 _B)	174 (AE _H)	-0.22 %
2400 Baud	4 (BRPRE=010 _B)	174 (AE _H)	-0.22 %

The fractional divider allows baud rates of higher accuracy (lower deviation error) to be generated. **Table 27** lists the resulting deviation errors from generating a baud rate of

3.11.2 Baud Rate Generation using Timer 1

In UART modes 1 and 3, Timer 1 can be used for generating the variable baud rates. In theory, this timer could be used in any of its modes. But in practice, it should be set into auto-reload mode (Timer 1 mode 2), with its high byte set to the appropriate value for the required baud rate. The baud rate is determined by the Timer 1 overflow rate and the value of SMOD as follows:

$$\text{Mode 1, 3 baud rate} = \frac{2^{\text{SMOD}} \times f_{\text{PCLK}}}{32 \times 2 \times (256 - \text{TH1})} \quad [3.1]$$

3.12 Normal Divider Mode (8-bit Auto-reload Timer)

Setting bit FDM in register FDCON to 1 configures the fractional divider to normal divider mode, while at the same time disables baud rate generation (see [Figure 29](#)). Once the fractional divider is enabled (FDEN = 1), it functions as an 8-bit auto-reload timer (with no relation to baud rate generation) and counts up from the reload value with each input clock pulse. Bit field RESULT in register FDRES represents the timer value, while bit field STEP in register FDSTEP defines the reload value. At each timer overflow, an overflow flag (FDCON.NDOV) will be set and an interrupt request generated. This gives an output clock f_{MOD} that is 1/n of the input clock f_{DIV} , where n is defined by 256 - STEP.

The output frequency in normal divider mode is derived as follows:

$$f_{\text{MOD}} = f_{\text{DIV}} \times \frac{1}{256 - \text{STEP}} \quad [3.2]$$

Functional Description

The block diagram of the CCU6 module is shown in **Figure 32**.

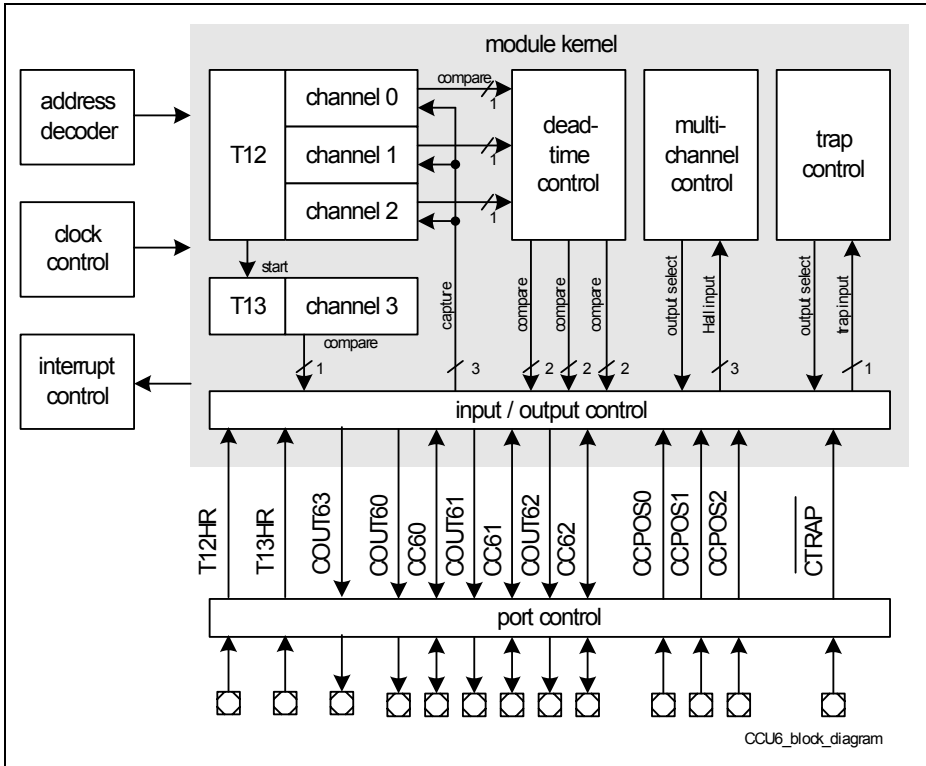


Figure 32 CCU6 Block Diagram

Electrical Parameters

Table 34 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions Remarks
			min.	max.		
Input low voltage at XTAL1	V_{ILX}	SR	$V_{SS} - 0.5$	$0.3 \times V_{DDC}$	V	
Input high voltage at XTAL1	V_{IHx}	SR	$0.7 \times V_{DDC}$	$V_{DDC} + 0.5$	V	
Pull-up current	I_{PU}	SR	–	-10	μA	$V_{IH,min}$
			-150	–	μA	$V_{IL,max}$
Pull-down current	I_{PD}	SR	–	10	μA	$V_{IL,max}$
			150	–	μA	$V_{IH,min}$
Input leakage current ²⁾	I_{OZ1}	CC	-1	1	μA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 125^\circ C$, XC866-4FR and XC866-2FR
			-2.5	1	μA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 125^\circ C$, XC866-1FR and ROM device
Input current at XTAL1	I_{ILX}	CC	-10	10	μA	
Overload current on any pin	I_{OV}	SR	-5	5	mA	
Absolute sum of overload currents	$\Sigma I_{OV} $	SR	–	25	mA	3)
Voltage on any pin during V_{DDP} power off	V_{PO}	SR	–	0.3	V	4)
Maximum current per pin (excluding V_{DDP} and V_{SS})	I_M	SR	–	15	mA	
Maximum current for all pins (excluding V_{DDP} and V_{SS})	$\Sigma I_M $	SR	–	60	mA	
Maximum current into V_{DDP}	I_{MVDDP}	SR	–	80	mA	
Maximum current out of V_{SS}	I_{MVSS}	SR	–	80	mA	

Electrical Parameters
Table 34 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Conditions Remarks
		min.	max.		
Pull-up current	I_{PU} SR	–	-5	μA	$V_{IH,min}$
		-50	–	μA	$V_{IL,max}$
Pull-down current	I_{PD} SR	–	5	μA	$V_{IL,max}$
		50	–	μA	$V_{IH,min}$
Input leakage current ²⁾	I_{OZ1} CC	-1	1	μA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 125^\circ C$, XC866-4FR and XC866-2FR
		-2.5	1	μA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 125^\circ C$, XC866-1FR and ROM device
Input current at XTAL1	I_{ILX} CC	- 10	10	μA	
Overload current on any pin	I_{OV} SR	-5	5	mA	
Absolute sum of overload currents	$\Sigma I_{OV} $ SR	–	25	mA	³⁾
Voltage on any pin during V_{DDP} power off	V_{PO} SR	–	0.3	V	⁴⁾
Maximum current per pin (excluding V_{DDP} and V_{SS})	I_M SR	–	15	mA	
Maximum current for all pins (excluding V_{DDP} and V_{SS})	$\Sigma I_M $ SR	–	60	mA	
Maximum current into V_{DDP}	I_{MVDDP} SR	–	80	mA	
Maximum current out of V_{SS}	I_{MVSS} SR	–	80	mA	

¹⁾ Not subjected to production test, verified by design/characterization. Hysteresis is implemented to avoid meta stable states and switching due to internal ground bounce. It cannot be guaranteed that it suppresses switching due to external system noise.

²⁾ An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin. TMS pin and RESET pin have internal pull devices and are not included in the input leakage current characteristic.

³⁾ Not subjected to production test, verified by design/characterization.

4.2.2 Supply Threshold Characteristics

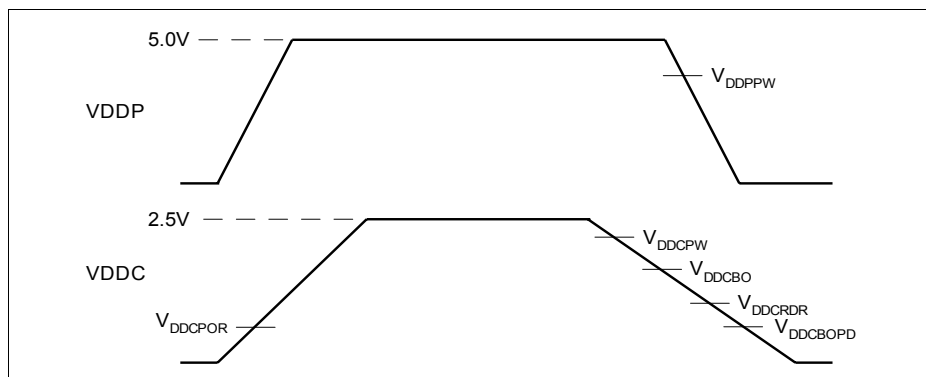


Figure 36 Supply Threshold Parameters

Table 35 Supply Threshold Parameters (Operating Conditions apply)

Parameters	Symbol		Limit Values			Unit	Remarks
			min.	typ.	max.		
V_{DDC} prewarning voltage ¹⁾	V_{DDCPW}	CC	2.2	2.3	2.4	V	
V_{DDC} brownout voltage in active mode ¹⁾	V_{DDCBO}	CC	2.0	2.1	2.2	V	XC866-4FR, XC866-2FR
			2.0	2.1	2.3	V	XC866-1FR, ROM device
RAM data retention voltage	V_{DDCRDR}	CC	0.9	1.0	1.1	V	
V_{DDC} brownout voltage in power-down mode ²⁾	$V_{DDCBOPD}$	CC	1.3	1.5	1.7	V	
V_{DDP} prewarning voltage ³⁾	V_{DDPPW}	CC	3.4	4.0	4.6	V	
Power-on reset voltage ²⁾⁴⁾	V_{DDCPOR}	CC	1.3	1.5	1.7	V	

¹⁾ Detection is disabled in power-down mode.

²⁾ Detection is enabled in both active and power-down mode.

³⁾ Detection is enabled for external power supply of 5.0V.
Detection must be disabled for external power supply of 3.3V.

⁴⁾ The reset of EVR is extended by 300 μ s typically after the V_{DDC} reaches the power-on reset voltage.

5.2 Package Outline

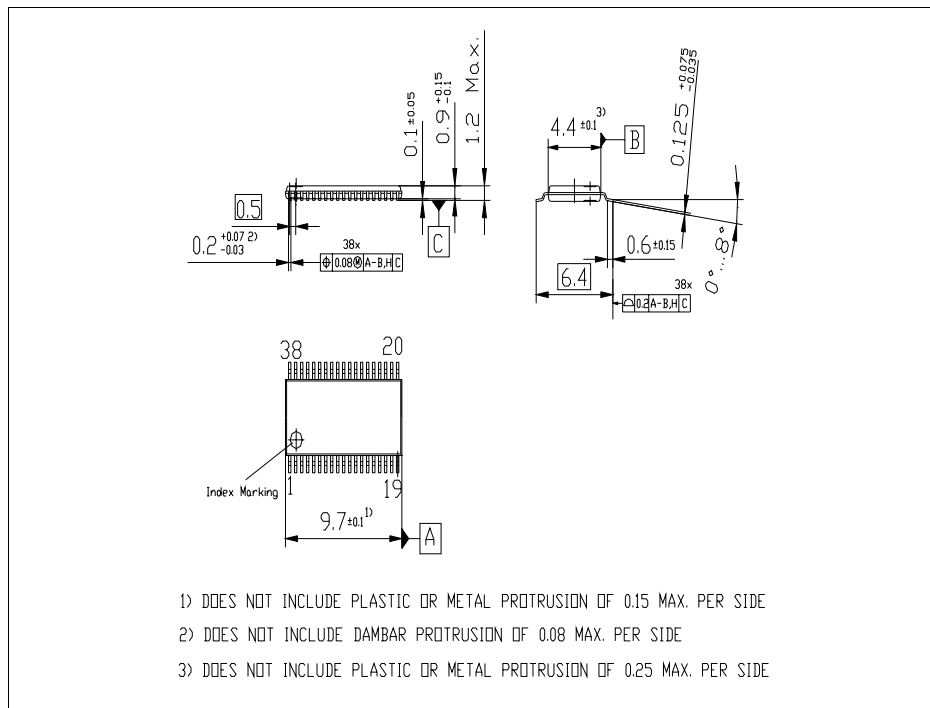


Figure 46 PG-TSSOP-38-4 Package Outline